



# CSP-27 Lead Free RoHS Profile

Total Mass of the Unit specified (g)	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.020	27 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	14.861650	730,573	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.008881	437	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.005515	271	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.002758	136	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.002758	136	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.021968	1,080	
		Metalization	BCB			0.033373	1,641	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	5.162361	253,773	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.216196	10,628	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.027000	1,327	

Total mass (mg)	20.342
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